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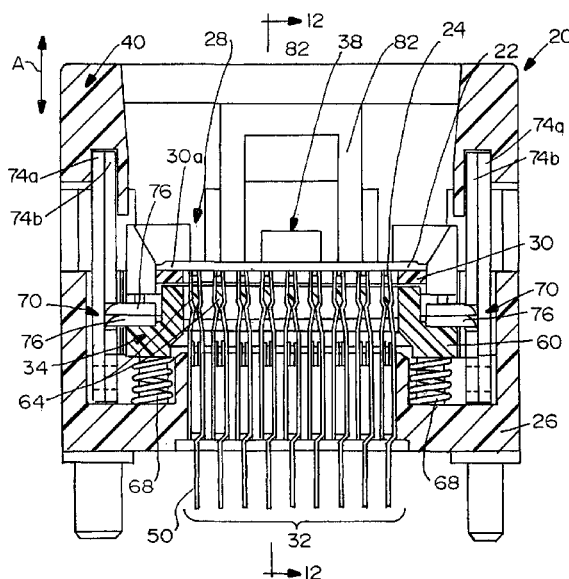
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(54) Title: IC TEST SOCKET



(57) **Abstract:** A burn-in socket is provided for testing an IC package having an array of solder balls on a bottom surface thereof. The socket including a body having a receptacle for receiving the IC package. A plurality of terminals are mounted on the body, with contact portions of the terminals exposed in the receptacle for engaging the solder balls of the IC package. The contact portion of each terminal is bifurcated to define a pair of opposing jaws for engaging the sides of a respective one of the solder balls therebetween. A spreader mechanism is movably mounted on the socket body for spreading the jaws in opposite directions to allow the solder balls of the IC package to be inserted between the spread jaws in a continuous linear motion as the IC package is inserted into the receptacle.